

Appl. No: 10/614,845
Reply to Office action of December 22, 2005

Amendments to the Specification:

Please replace the paragraph beginning at page 1 line 3 with the following amended paragraph:

This application is a continuation of copending U.S. Serial No. 09/988,901 entitled "Nanostructured Deposition and Devices", filed November 19, 2001, which is a continuation of U.S. Serial No. ~~08/251,313~~ 09/251,313 entitled "Nanostructured Solid Electrolytes and devices, now issued as U.S. Patent 6,387,560, filed on February 17, 1999, which is a continuation of U.S. Serial No. 08/739,257, entitled "Nanostructured Ion Conducting Solid Electrolytes", now issued as U.S. Patent 5,905,000, filed October 30, 1996, which is a continuation-in-part of U.S. Serial No. 08/730,661, entitled "Passive Electronic Components from Nano-Precision Engineered Materials," filed on October 11, 1996, which is a continuation-in-part of U.S. Serial No. 08/706,819, entitled "Integrated Thermal Process and Apparatus for the Continuous Synthesis of Nanoscale Powders" now issued as U.S. Patent No. 5,851,507 on December 22, 1998, and U.S. Serial No. 08/707,341, entitled "~~Boundary Layer Joule Thompson Nozzle for Thermal Quenching of High Temperature Vapors~~ Method Of Producing Nanoscale Powders By Quenching Of Vapors," filed concurrently on September 3, 1996, now issued as US. Patent No. 5,788,738 on August 4, 1998. These applications and patents are all commonly owned with the present application, and are all incorporated by reference herein.